



# Test Report

**Sample Name:** \_\_\_\_\_ The integrated circuit

**Part Number:** \_\_\_\_\_ XCF02SVO20C

**Manufacturer:** \_\_\_\_\_ XILINX

**Customer:** \_\_\_\_\_

Shenzhen Chuangxin Online Testing Service Co., Ltd.

November 07, 2024

# Test Report

Customer:

Customer Address:

Sample Name: The Integrated Circuit

Part Number: XCF02SVO20C

Manufacturer: XILINX

Date Code: N/A

Package Type: TSSOP-20

Quantity Received: 64 PCS

Quantity Inspected: 64 PCS

Date Received: 11/05/2024

Date Tested: 11/06/2024/15: 40 - 11/06/2024/17: 50

Tested by \_\_\_\_\_

Issued by

Inspected by \_\_\_\_\_

(Stamp)

Approved by \_\_\_\_\_

## Test Items

External visual inspection

Pin correlation test

Programming test

Solderability analysis

Radiography(X-ray)

XRF test

Key functional test(KFT)

Baking

Tape and reel

Top permanency test

Internal visual inspection

SAT test

Cross section

## Methods & Equipment

### 1.1 Test standard:

- **AS6081A-2023**

### 1.2 Optical microscope:

- Equipment spec:

Optical microscope: SEZ-260 X7-X45(Due date: 07/17/2025)

### 1.3 Functional test equipment:

- Equipment spec:

Xeltek programming unit: 6100N(Due date: 07/17/2025)

### 1.4 Datasheet Reference:

- 《XILINX XCF02SVO20C》 :

<https://docs.amd.com/v/u/en-US/ds123>

# Analysis Summary

## Programming test results:

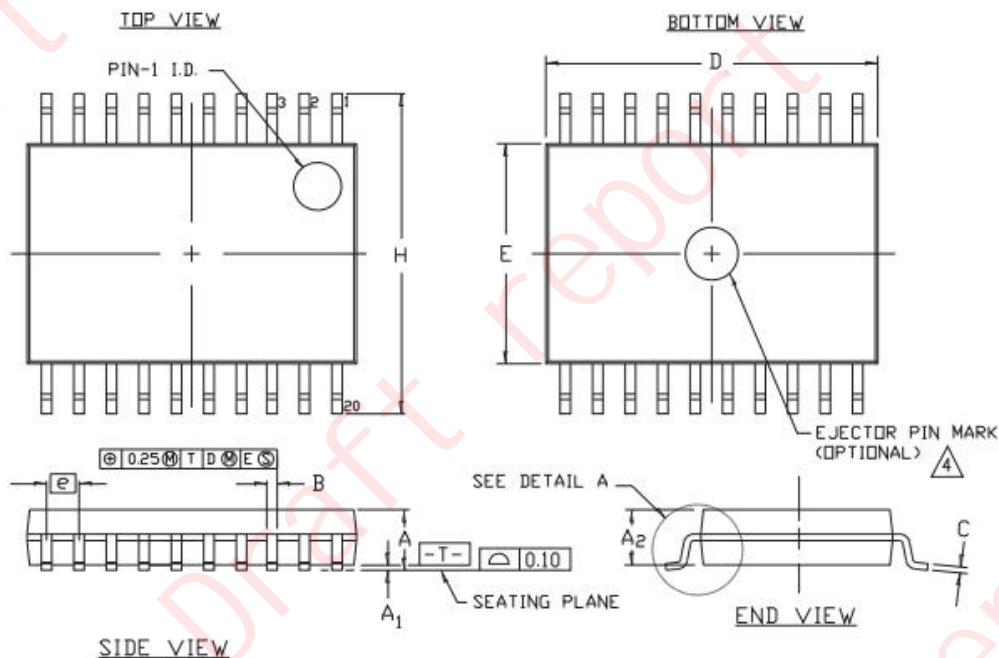
<b>Programming test</b>	<b>Results:</b>
<b>Total quantity tested</b>	64 PCS
<b>Total quantity passed</b>	64 PCS
<b>Total quantity failed</b>	0 PCS
<b>Note</b>	All devices passed programming test.

<b>Programming test results</b>	
<b>Tested parameters</b>	<b>Results</b>
<b>Pin continuity</b>	Pass
<b>ID check</b>	Pass
<b>Erase</b>	Pass
<b>Blank check</b>	Pass
<b>Program</b>	Pass
<b>Verify</b>	Pass
<b>Erase</b>	Pass
<b>Blank check</b>	Pass

## 1. Device description:

Xilinx introduces the Platform Flash series of in-system programmable configuration PROMs. Available in 1 to 32 Mb densities, these PROMs provide an easy-to-use, cost-effective, and reprogrammable method for storing large Xilinx FPGA configuration bitstreams.

## 2. Package dimensions:



SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	--	--	1.19
A <sub>1</sub>	0.05	0.10	0.15
A <sub>2</sub>	0.79	--	1.04
B	0.18	--	0.30
C	0.10	--	0.20
D	6.40	6.50	6.60
E	4.29	4.39	4.47
e	0.65 BSC		
H	6.20	6.40	6.60
L	0.50	0.60	0.75
α	0°	5°	8°

### NOTES:

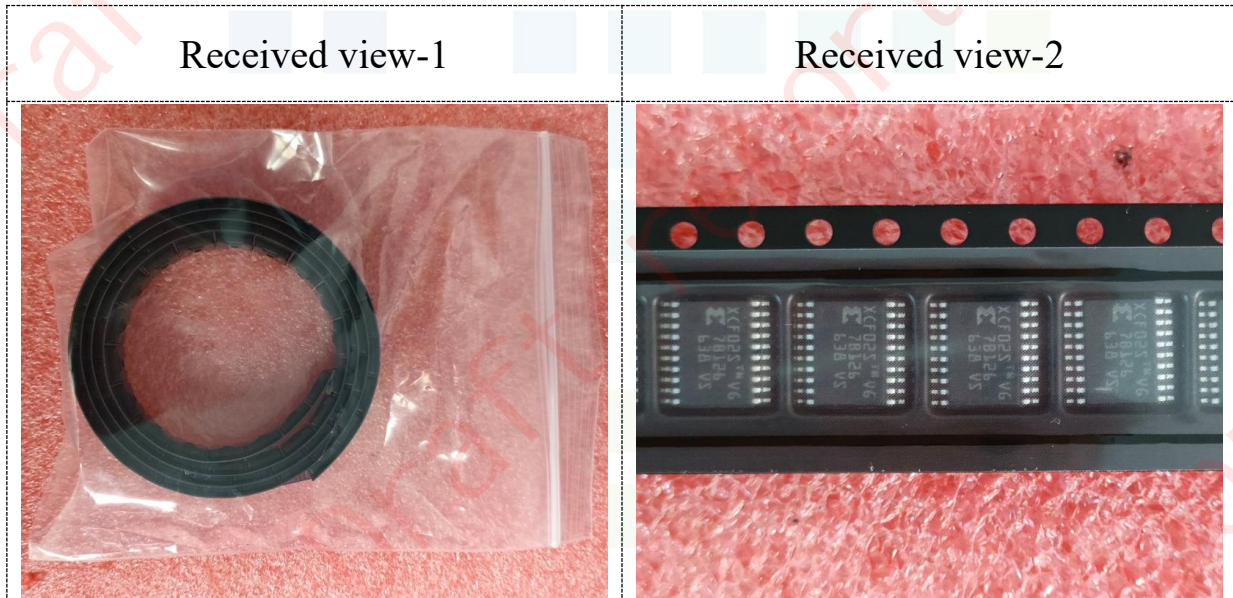
- ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982.
- DIMENSION "D" DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED 0.15mm PER SIDE
- DIMENSION "E" DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE
- EJECTOR PIN MARK IS A ROUND IMPRESSION MADE BY MACHINE DURING ASSEMBLY PROCESS
- LEAD FINISH: VO20 - 85/15 (Sn/Pb)  
VOG20 - 100% Matte Sn
- CONFORMS TO JEDEC MO-153-AC

pk068\_01\_022812

### 3. Documentation and packaging inspection:

<b>Gross Weight</b>	9.0 g	<b>Quantity Received</b>	64 PCS
<b>Number of Boxes</b>	N/A	<b>Full Label</b>	N/A
<b>Package Type</b>	Reel	<b>Moisture Protection</b>	N/A
<b>MSL</b>	N/A	<b>ESD Protection</b>	N/A

Note: All devices contain 64 PCS samples.



## 4. Programming test:

Applicable standard: **AS6081A-2023**

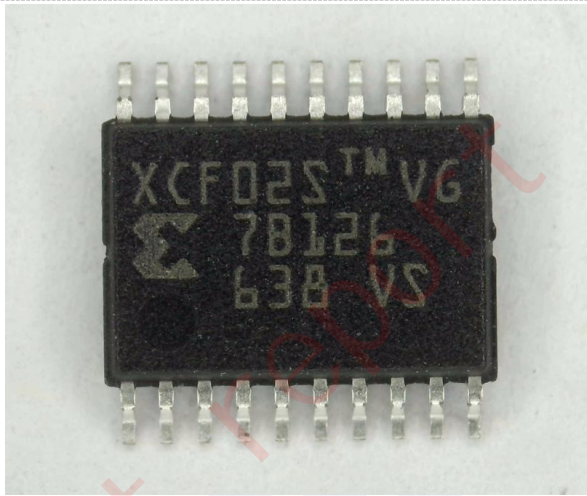
Ambient temperature: 24.8 °C Relative humidity: 52.5 % RH

Devices were tested for the followings using Xeltek platform:

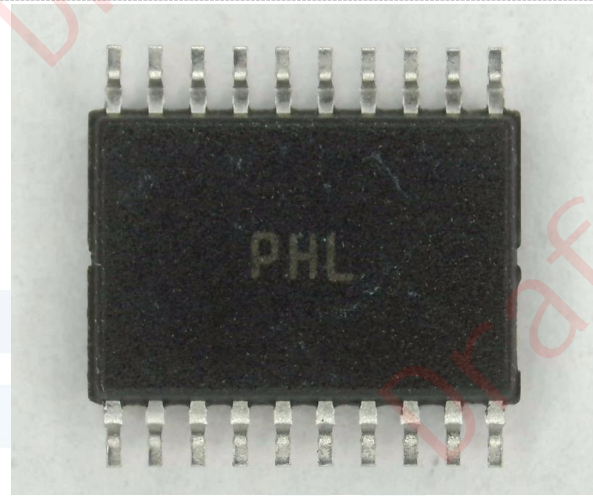
- Pin continuity: Wrong chip insertion check. Prevent chips from accidental damage.
- ID Check: Device ID is the code read from the chip to identify the manufacturer and the device type. If the device ID is unmatched, an error will occur.
- Erase: Erase the chip to blank state. This operation can only be executed with the chip that can be erased electrically.
- Blank Check: Ensure no program on device.
- Program: Devices are programmed with random data.
- Verify: The function compares the content of the buffer to that of the chip. If there is any discrepancy, verification will cease and failure message will be displayed. Only the chips that pass verification can be recognized as chips being programmed correctly.
- Erase: Erase the chip to blank state. This operation can only be executed with the chip that can be erased electrically.
- Blank Check: Ensure no program on device.



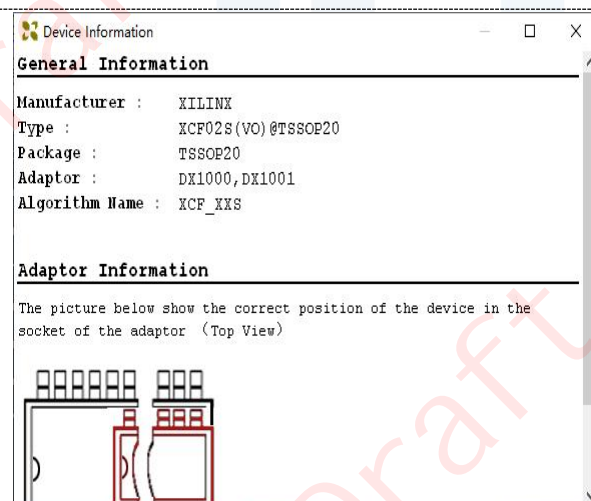
Top



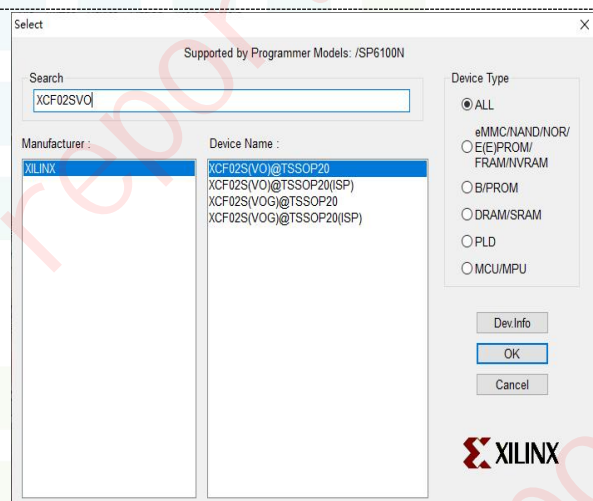
Bottom



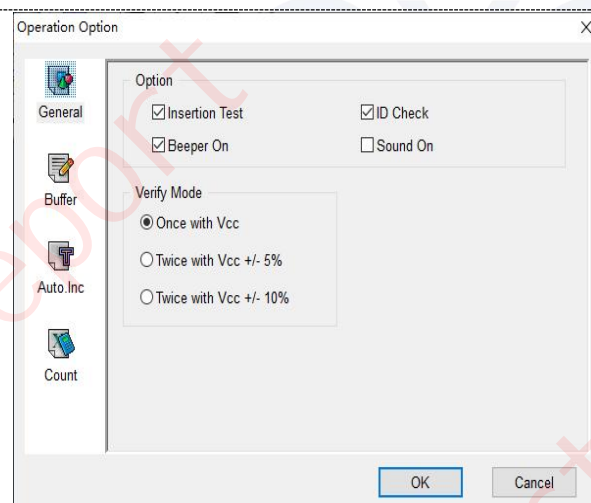
Device Information



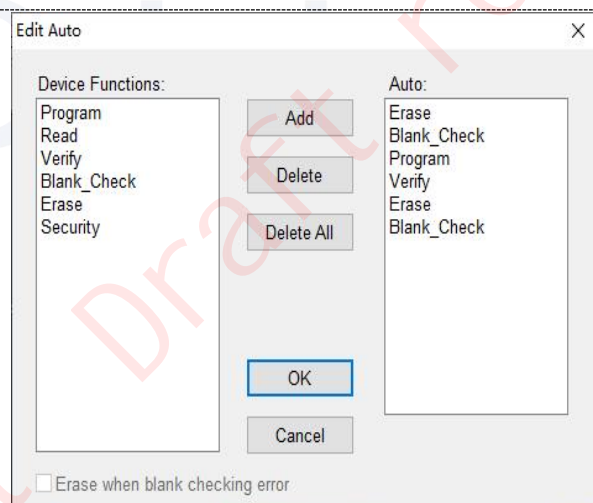
Select Parts



Operation Option

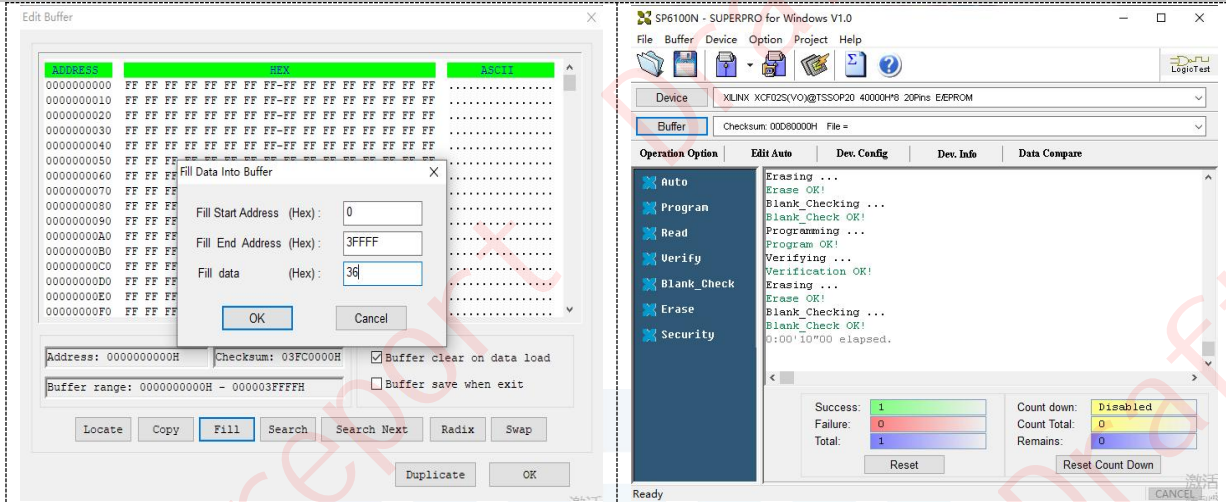


Edit Auto



Edit Buffer

Test result (Pass)



<b>Programming test</b>	<b>Results:</b>
<b>Total quantity tested</b>	64 PCS
<b>Total quantity passed</b>	64 PCS
<b>Total quantity failed</b>	0 PCS
<b>Note</b>	All devices passed programming test.

-End of Report-

## Disclaimer

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2. The copy of the test report is invalid without the stamp of “company report seal” and “cross-page seal”.
3. The test report is invalid without the signatures of operator, supervisor and manager.
4. A modified or partial copy of the test report is invalid.
5. When there is disagreement with the test report, please submit the issue to us within 15 days from the date of receipt. Overdue information will not be accepted.
6. The test report is only reflective of the test results of testing samples, not of the quality of batch products.
7. The \* indicates subcontract test data.
8. The report is stamped with the CMA mark, indicating that the test items are within the scope of qualification recognition; No CMA mark is stamped, indicating that some/all of the test items are not within the scope of CMA qualification, and the results are for internal use by the customer only.



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